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SGLS350C -JULY 2006-REVISED SEPTEMBER 2010

BACKUP-BATTERY SUPERVISORS FOR RAM RETENTION

Check for Samples: TPS3619-33-EP, TPS3619-50-EP, TPS3620-33-EP, TPS3620-50-EP

FEATURES

- Supply Current of 40 μA (Max)
- Battery-Supply Current of 100 nA (Max)
- Precision Supply-Voltage Monitor 3.3 V, 5 V, and Other Options on Request
- Backup-Battery Voltage Can Exceed V_{DD}
- Power-On Reset Generator with Fixed 100-ms
 Reset Delay Time
- Voltage Monitor for Power-Fail or Low-Battery Monitoring
- Battery Freshness Seal (TPS3619)
- Pin-to-Pin Compatible With MAX819, MAX703, and MAX704
- 8-Pin Mini Small-Outline Package (MSOP) Package

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Military (–55°C/125°C)
 Temperature Range⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability
- (1) Additional temperature ranges available contact factory

APPLICATIONS

- Fax Machines
- Set-Top Boxes
- Advanced Voice-Mail Systems
- Portable Battery-Powered Equipment
- Computer Equipment
- Advanced Modems
- Automotive Systems
- Portable Long-Time Monitoring Equipment
- Point-of-Sale Equipment

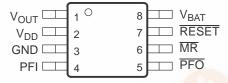
DESCRIPTION

The TPS3619 and TPS3620 families of supervisory circuits monitor and control processor activity by providing backup-battery switchover for data retention of CMOS RAM.

During power on, \overline{RESET} is asserted when the supply voltage (V_{DD} or V_{BAT}) becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors V_{DD} and keeps \overline{RESET} output active as long as V_{DD} remains below the threshold voltage (V_{IT}). An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time starts after V_{DD} has risen above V_{IT}. When the supply voltage drops below V_{IT}, the output becomes active (low) again.

The product spectrum is designed for supply voltages of 3.3 V and 5 V. The TPS3619 and TPS3620 are available in an 8-pin MSOP package and are characterized for operation over a temperature range of -55°C to 125°C.





ACTUAL SIZE 3,05 mm x 4,98 mm



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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

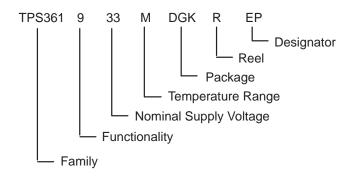
TYPICAL OPERATING CIRCUIT Power **TPS3619** Microcontroller **TPS3620 Backup Battery** Microprocessor V_{DD} V_{BAT} External Ī Source RESET RESET PFO **Switchover** Capacitor MR V_{OUT} v_{cc} Manual **GND GND** Reset 丰

PACKAGE INFORMATION(1)

T _A	PRODUCT	PACKAGE MARKING	ORDERABLE PART NUMBER	TRANSPORT MEDIA, QUANTITY	
TD00040.00		D7D	TPS3619-33MDGKEP ⁽²⁾	Tube, 80	
	TPS3619-33 BZP		TPS3619-33MDGKREP	Tape and reel, 2500	
	TPS3619-50 TPS3620-33	TBD	TPS3619-50MDGK ⁽²⁾	Tube, 80	
–55°C to 125°C		טפו	TPS3619-50MDGKREP ⁽²⁾	Tape and reel, 2500	
		BTY	TPS3620-33MDGKTEP	Tape and reel, 250	
	1733020-33	DIT	TPS3620-33MDGKREP	Tape and reel, 2500	
	TDC2020 F0	TDD	TPS3620-50MDGKTEP ⁽²⁾	Tape and reel, 250	
	TPS3620-50	TBD	TPS3620-50MDGKREP ⁽²⁾	Tape and reel, 2500	

- (1) For the most current specifications and package information, see the Package Option Addendum located at the end of this data sheet or see the TI web site at www.ti.com.
- (2) Product Preview. Parameters in electrical characteristics are subject to change.

Standard and Application-Specific Versions



NOMINAL VOLTAGE ⁽¹⁾ , V _{NOM}
3.3 V
5 V
3.3 V
5 V

 For other threshold voltage versions, contact the local TI sales office for availability and lead time.



<u>₩豐梅*PPS3619-33 EP"供应商</u>

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Absolute Maximum Ratings

over operating free-air temperature (unless otherwise noted)(1)

		UNIT
Complement	V _{DD} (2)	7 V
Supply voltage	MR and PFI pins ⁽²⁾	-0.3 V to (V _{DD} + 0.3 V)
Continuous output current, I _O	V _{OUT}	400 mA
	All other pins ⁽²⁾	±10 mA
Continuous total power dissipation		See Dissipation Ratings Table
Operating free-air temperature range, T _A		−55°C to 125°C
Storage temperature range, T _{stg}		−65°C to 150°C
Lead temperature soldering 1,6 mm (1/16 in) from case for 10 s		260°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Dissipation Ratings

PACKAGE	T _A < 25°C	DERATING FACTOR	T _A = 70°C	T _A = 85°C	T _A = 125°C
	POWER RATING	ABOVE T _A = 25°C	POWER RATING	POWER RATING	POWER RATING
DGK	470 mW	3.76 mW/°C	301 mW	241 mW	93.98 mW

Recommended Operating Conditions

at specified temperature range

•	· · · · · · · · · · · · · · · · · · ·	MIN	MAX	UNIT
V_{DD}	Supply voltage	1.65	5.5	V
V_{BAT}	Battery supply voltage	1.5	5.5	V
VI	Input voltage	0	V _{DD} + 0.3	V
V_{IH}	High-level input voltage	$0.7 \times V_{DD}$		V
V_{IL}	Low-level input voltage		$0.3 \times V_{DD}$	V
Io	Continuous output current at V _{OUT}		300	mA
	Input transition rise and fall rate at MR		100	ns/V
Δt/ΔV	Slew rate at V _{DD} or V _{BAT}		1	V/μs
T _A	Operating free-air temperature	-55	125	°C

⁽²⁾ All voltage values are with respect to GND. For reliable operation, the device must not be continuously operated at 7 V for more than t = 1000 h.



Electrical Characteristics

over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CON	DITIONS	MIN	TYP	MAX	UNIT	
		DECET	$V_{DD} = 3.3 \text{ V}, I_{OH} = -$	2 mA	V _{DD} - 0.4				
		RESET	$V_{DD} = 5 \text{ V}, I_{OH} = -3$	mA	V _{DD} – 0.4			V	
V_{OH}	High-level output voltage		V _{DD} = 1.8 V, I _{OH} = -	20 μΑ	V _{DD} – 0.3				
		PFO	$V_{DD} = 3.3 \text{ V}, I_{OH} = -80 \mu\text{A}$		V _{DD} – 0.4				
			$V_{DD} = 5 \text{ V}, I_{OH} = -12$	20 μΑ	V _{DD} – 0.4				
			$V_{DD} = 1.8 \text{ V}, I_{OL} = -4$	400 μΑ			0.2		
V_{OL}	Low-level output voltage	RESET, PFO	$V_{DD} = 3.3 \text{ V}, I_{OL} = 2$	mA			0.4	V	
			$V_{DD} = 5 \text{ V}, I_{OL} = 3 \text{ m}$	nA			0.4		
V _{res}	Power-up reset voltage ⁽¹⁾		$I_{OL} = 20 \mu A, V_{BAT} > V_{DD} > 1.1 V$	1.1 V or			0.4	V	
			$I_{OUT} = 8.5 \text{ mA}, V_{BAT}$ $V_{DD} = 1.8 \text{ V}$	= 0 V,	V _{DD} – 50				
	Normal mode		$I_{OUT} = 125 \text{ mA}, V_{BA}$ $V_{DD} = 3.3 \text{ V}$	r = 0 V,	V _{DD} – 150				
V _{OUT}			I _{OUT} = 190 mA, V _{BA} - V _{DD} = 5 V	r = 0 V,	V _{DD} – 200			mV	
	Battery-backup mode		$I_{OUT} = 0.5 \text{ mA}, V_{BAT}$ $V_{DD} = 0 \text{ V}$	= 1.5 V,	V _{BAT} – 50				
			$I_{OUT} = 7.5 \text{ mA}, V_{BAT} = 3.3 \text{ V}$		V _{BAT} – 150				
	V _{DD} to V _{OUT} on resistance		$V_{DD} = 5 V$			0.6	1	Ω	
r _{DS(on)}	V _{BAT} to V _{OUT} on resistance		V _{DD} = 3.3 V			8	20	12	
V_{IT-}		TPS36XX-33	T _A = -55°C to 125°C		2.88	2.93	3.05	٧	
V -	Negative-going input threshold voltage (2)	TPS36XX-50			4.46	4.55	4.64		
V_{PFI}			$T_A = -55^{\circ}C$ to 125°C		1.13	1.15	1.185	V	
		V _{IT}	1.65 V < V _{IT} < 2.5 V		20				
			2.5 V < V _{IT} < 3.5 V			40			
V_{hys}	Hysteresis		$3.5 \text{ V} < \text{V}_{\text{IT}} < 5.5 \text{ V}$			60		mV	
		PFI				12			
		VBSW ⁽³⁾	V _{DD} = 1.8 V			55			
I _{IH}	High-level input current	MR	$\overline{MR} = 0.7 \times V_{DD}$	$V_{DD} = 5 V$	-30		-76	μΑ	
I _{IL}	Low-level input current	MR	$\overline{MR} = 0 \text{ V},$	$V_{DD} = 5 V$	-110		-255	μΑ	
l _l	Input current	PFI			-25		25	nA	
Ios				V _{DD} = 1.8 V			-0.3		
	Short-circuit current	PFO	PFO = 0 V	V _{DD} = 3.3 V			-1.1	mA	
				V _{DD} = 5 V			-2.4		
I _{DD}	V _{DD} supply current		$V_{OUT} = V_{DD}$ $V_{OUT} = V_{BAT}$				40	μΑ	
		DD Sappiy Surroit						40	
I _(BAT)	V _{BAT} supply current		$V_{OUT} = V_{DD}$		-0.1		0.1	μΑ	
			V _{OUT} = V _{BAT}				0.5		
CI	Input capacitance		$V_I = 0 V \text{ to } 5 V$			5		pF	

The lowest supply voltage at which \overline{RESET} becomes active. $t_{r,VDD} \ge 15~\mu s/V$. To ensure the best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be placed near the supply terminals. For $V_{DD} < 1.6~V$, V_{OUT} switches to V_{BAT} , regardless of V_{BAT} .

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Timing Requirements

at $R_L = 1 \text{ M}\Omega$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$

PARAMETER		1	TEST CONDITIONS	MIN MAX	UNIT
	Duloo width	at V _{DD}	$V_{IH} = V_{IT} + 0.2 \text{ V}, V_{IL} = V_{IT} - 0.2 \text{ V}$	6	μS
ı _w	Pulse width	at MR	$V_{DD} = V_{IT} + 0.2 \text{ V}, V_{IL} = 0.3 \text{ x } V_{DD}, V_{IH} = 0.7 \text{ x } V_{DD}$	100	ns

Switching Characteristics

at $R_1 = 1 \text{ M}\Omega$, $C_1 = 50 \text{ pF}$, $T_{\Delta} = -55^{\circ}\text{C}$ to 125°C

	PARAMETE	R	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _d	Delay time		$V_{DD} \ge V_{IT} + 0.2 \text{ V}, \overline{\text{MR}} \ge 0.7 \times V_{DD},$ See timing diagram	60	100	140	ms
		V _{DD} to RESET	$V_{IL} = V_{IT} - 0.4 \text{ V}, V_{IH} = V_{IT} + 0.4 \text{ V}$		2	5	
t _{PHL}	Propagation (delay) time,	PFI to PFO delay	$V_{IL} = V_{PFI} - 0.35 \text{ V}, V_{IH} = V_{PFI} + 0.35 \text{ V}$		3	5	นร
PHL	high-to-low-level output	MR to RESET	$V_{DD} \ge V_{IT} + 0.2 \text{ V}, V_{IL} = 0.3 \times V_{DD}, V_{IH} = 0.7 \times V_{DD}$		0.1	1	μο

Timing Diagram

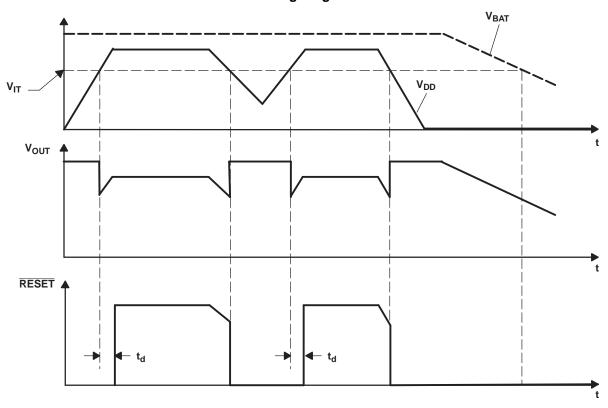




Table 1. FUNCTION TABLE

$V_{DD} > V_{IT}$	$V_{DD} > V_{BAT}$	MR	V _{OUT}	RESET
0	0	L	V_{BAT}	L
0	0	Н	V_{BAT}	L
0	1	L	V_{DD}	L
0	1	Н	V_{DD}	L
1	0	L	V_{DD}	L
1	0	Н	V_{DD}	Н
1	1	L	V_{DD}	L
1	1	Н	V_{DD}	Н

PFI > V _{PFI}	PFO		
0	L		
1	Н		
CONDITION: V _{DD} > V _{DD} (MIN)			

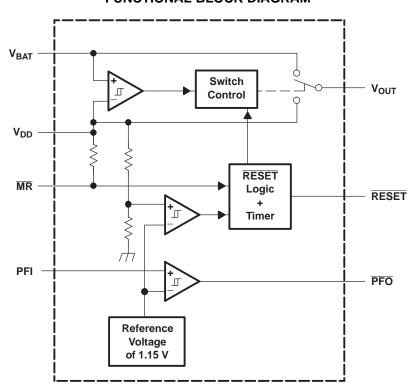
TERMINAL FUNCTIONS

TERI	TERMINAL		DECORPORION	
NAME	NO.	1/0	DESCRIPTION	
GND	3	ı	Ground	
MR	6	1	Manual reset	
PFI	4	1	Power-fail comparator input	
PFO	5	0	Power-fail comparator output	
RESET	7	0	Active-low reset	
V_{BAT}	8	1	Backup battery	
V_{DD}	2	I	Supply input voltage	
V _{OUT}	1	0	Supply output voltage	

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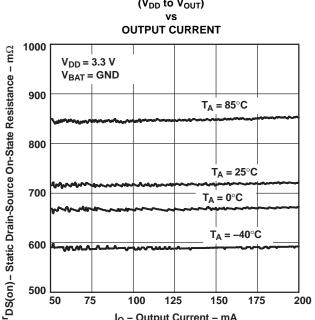
FUNCTIONAL BLOCK DIAGRAM





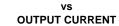
TYPICAL CHARACTERISTICS

STATIC DRAIN-SOURCE ON-STATE RESISTANCE $(V_{DD} \text{ to } V_{OUT})$



I_O – Output Current – mA Figure 1.

STATIC DRAIN-SOURCE ON-STATE RESISTANCE (V_{BAT} to V_{OUT})



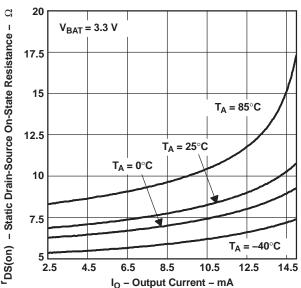
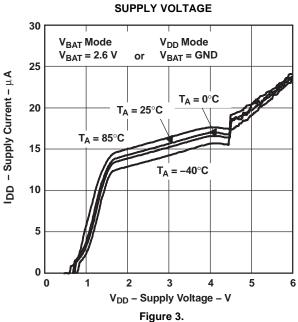


Figure 2.

SUPPLY CURRENT vs



NORMALIZED THRESHOLD AT RESET

FREE-AIR TEMPERATURE

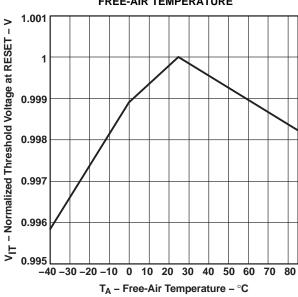
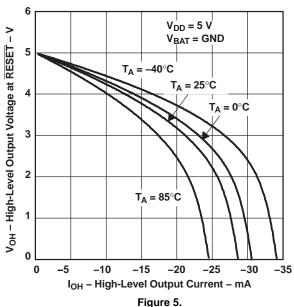


Figure 4.

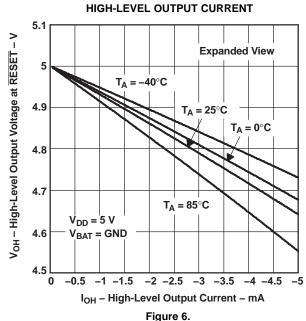
TYPICAL CHARACTERISTICS (continued)

HIGH-LEVEL OUTPUT VOLTAGE AT RESET

HIGH-LEVEL OUTPUT CURRENT

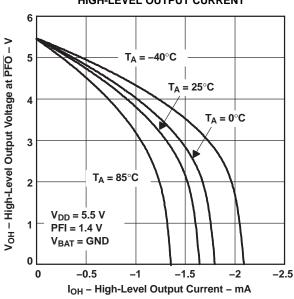


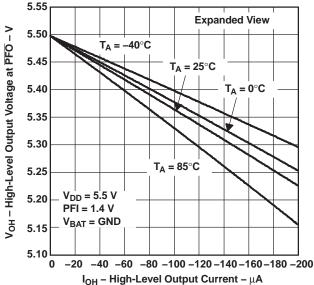
HIGH-LEVEL OUTPUT VOLTAGE AT RESET



HIGH-LEVEL OUTPUT VOLTAGE AT PFO

HIGH-LEVEL OUTPUT CURRENT





HIGH-LEVEL OUTPUT VOLTAGE AT PFO

HIGH-LEVEL OUTPUT CURRENT

Figure 7.

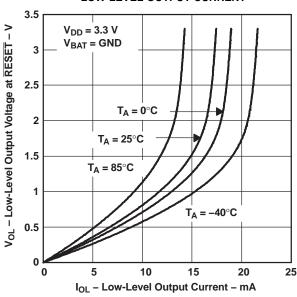
Figure 8.



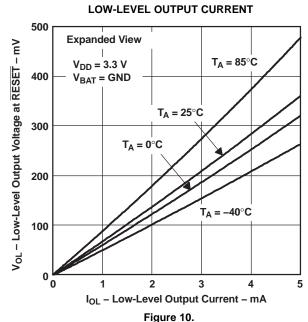
TYPICAL CHARACTERISTICS (continued)

LOW-LEVEL OUTPUT VOLTAGE AT RESET

LOW-LEVEL OUTPUT CURRENT



LOW-LEVEL OUTPUT VOLTAGE AT RESET



MINIMUM PULSE DURATION AT VDD THRESHOLD OVERDRIVE AT V_{DD}

Figure 9.

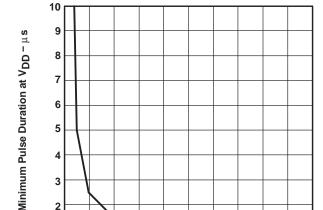
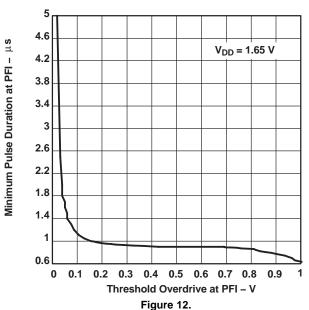


Figure 11.

Threshold Overdrive at V_{DD} - V

MINIMUM PULSE DURATION AT PFI

THRESHOLD OVERDRIVE AT PFI



0.4 0.5

0.6 0.7

0.3

2

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DETAILED DESCRIPTION

Battery Freshness Seal (TPS3619)

The battery freshness seal of the TPS3619 family disconnects the backup battery from internal circuitry until it is needed. This function prevents the backup battery from being discharged until the final product is put to use. The following steps explain how to enable the freshness seal mode.

- 1. Connect V_{BAT} ($V_{BAT} > V_{BAT}$ min)
- 2. Ground PFO
- 3. Connect PFI to V_{DD} (PFI = V_{DD})
- 4. Connect V_{DD} to power supply $(V_{DD} > V_{IT})$ and retain for 5 ms < t < 35 ms

The battery freshness seal mode is removed automatically by the positive-going edge of \overline{RESET} when V_{DD} is applied.

Power-Fail Input/Output Comparator (PFI and PFO)

An additional comparator is provided to monitor voltages other than the nominal supply voltage. The PFI is compared with an internal voltage reference of 1.15 V. If the input voltage falls below the power-fail threshold $(V_{IT(PFI)})$ of 1.15 V (typ), the PFO goes low. If $V_{IT(PFI)}$ goes above $V_{(PFI)}$ plus about 12-mV hysteresis, the output returns to high. By connecting two external resistors, it is possible to supervise any voltages above $V_{(PFI)}$. The sum of both resistors should be about 1 M Ω , to minimize power consumption and also to ensure that the current in the PFI pin can be ignored, compared with the current through the resistor network. The tolerance of the external resistors should be not more than 1%, to ensure minimal variation of sensed voltage. If the power-fail comparator is unused, PFI should be connected to ground and \overline{PFO} left unconnected.

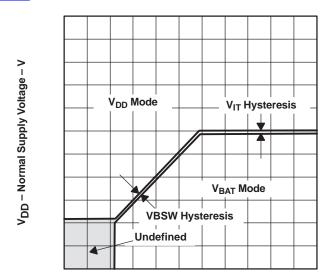
Backup-Battery Switchover

In case of a brownout or power failure, it may be necessary to preserve the contents of RAM. If a backup battery is installed at V_{BAT} , the device automatically switches the connected RAM to backup power when V_{DD} fails. In order to allow the backup battery (e.g., a 3.6-V lithium cell) to have a higher voltage than V_{DD} , these supervisors do not connect V_{BAT} to V_{OUT} when V_{BAT} is greater than V_{DD} . V_{BAT} only connects to V_{OUT} (through a 15- Ω switch) when V_{DD} falls below the V_{IT} and V_{BAT} is greater than V_{DD} . When V_{DD} recovers, switchover is deferred, either until V_{DD} crosses V_{BAT} or until V_{DD} rises above V_{IT} . V_{OUT} connects to V_{DD} through a 1- Ω (max) PMOS switch when V_{DD} crosses the reset threshold.

Table 2. FUNCTION TABLE

$V_{DD} > V_{BAT}$	$V_{DD} > V_{IT}$	V _{OUT}
1	1	V_{DD}
1	0	V_{DD}
0	1	V_{DD}
0	0	V_{BAT}





V_{BAT} – Backup-Battery Supply Voltage – V

Figure 13. Normal Supply Voltage vs Backup-Battery Supply Voltage





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pe
TPS3619-33MDGKREP	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS3620-33MDGKREP	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
TPS3620-33MDGKTEP	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
V62/06670-01XE	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
V62/06670-03XE	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retard in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKA

OTHER QUALIFIED VERSIONS OF TPS3619-33-EP, TPS3620-33-EP:

• Catalog: TPS3619-33, TPS3620-33

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product



查询"TPS3619-33-EP"供应商

16-Oct-2010

TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
		Overall width of the carrier tape
Γ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

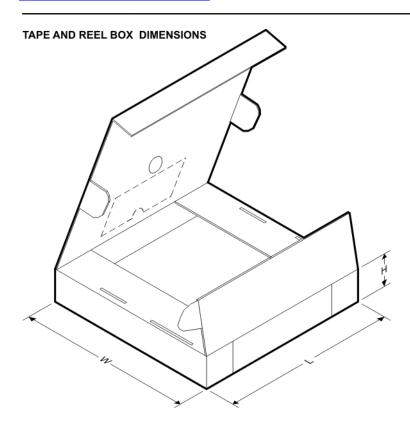


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3619-33MDGKREP	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS3620-33MDGKREP	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS3620-33MDGKTEP	MSOP	DGK	8	250	177.8	12.4	5.3	3.4	1.4	8.0	12.0	Q1

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16-Oct-2010

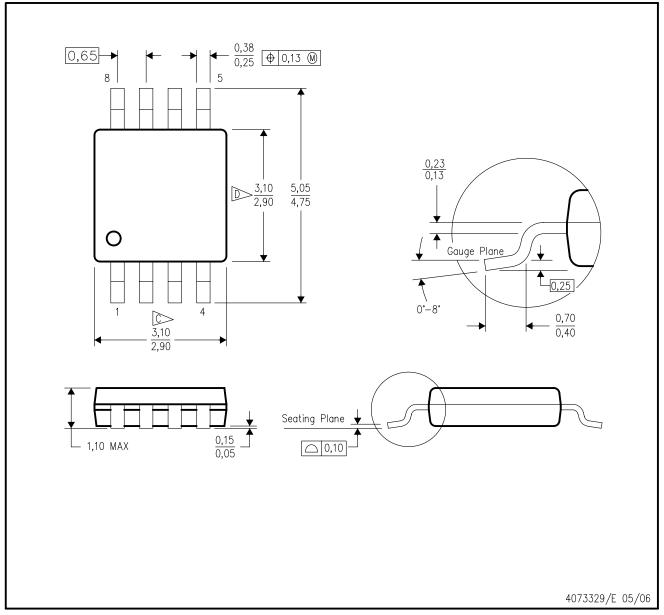


*All dimensions are nominal

7 III GITTOTOTOTO GITO TIGITIMI GI							
Device	Device Package Type		Pins	SPQ	SPQ Length (mm) Width (mm)		Height (mm)
TPS3619-33MDGKREP	MSOP	DGK	8	2500	358.0	335.0	35.0
TPS3620-33MDGKREP	MSOP	DGK	8	2500	358.0	335.0	35.0
TPS3620-33MDGKTEP	MSOP	DGK	8	250	202.0	201.0	28.0

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



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